



Material Content Data Sheet



Sales Product Name		BSC026N02KS G		Issued		19. January 2018		
MA#		MA001703086						
Package		PG-TDSON-8-39		Weight*		113.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.410	3.00	3.00	30019	30019
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.049	0.04		429	
	non noble metal	copper	7440-50-8	48.649	42.86	42.91	428295	428853
	non noble metal	copper	7440-50-8	0.036	0.03	0.03	315	315
wire	non noble metal	copper	7440-50-8	0.036	0.03	0.03	315	315
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		700	
	plastics	epoxy resin	-	6.284	5.53		55325	
	inorganic material	silicondioxide	60676-86-0	33.411	29.41	35.01	294135	350160
leadfinish	non noble metal	tin	7440-31-5	1.520	1.34	1.34	13382	13382
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1395	1395
solder	non noble metal	tin	7440-31-5	0.058	0.05		510	
	noble metal	silver	7440-22-4	0.072	0.06		637	
	non noble metal	lead	7439-92-1	2.765	2.43	2.54	24344	25491
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.150	0.13		1321	
	non noble metal	copper	7440-50-8	16.910	14.89	15.03	148870	150385
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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